



Product Change Notification

113318 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113318 - 00
Change Title: Intel® Server Pedestal Chassis Hot Swap Drive Kit FUP4X35HSDK
PCN 113318-00, Product Design
Add a bracket and remove the venting holes
Date of Publication: October 17, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Effective Immediately
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

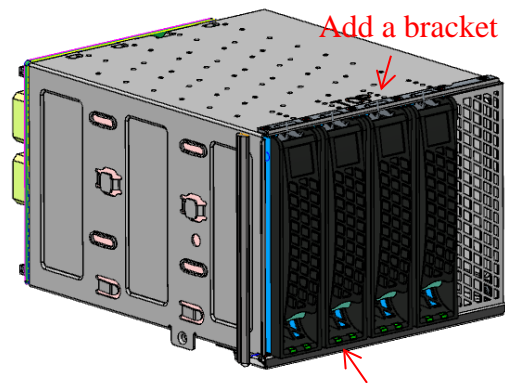
Description of Change to the Customer:

Intel has implemented the following change on the Intel® Server Pedestal Chassis Hot Swap Drive Kit FUP4X35HSDK:

- Add a bracket and remove the venting holes to improve the integration stability. Refer to the following pictures.



a) Pre-Change



Remove the venting holes

b) Post-Change

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
FUP4X35HSDK	911885	G21448-005	G21448-006

PCN Revision History:**Date of Revision:**

October 17, 2014

Revision Number:

00

Reason:

Originally Published PCN